

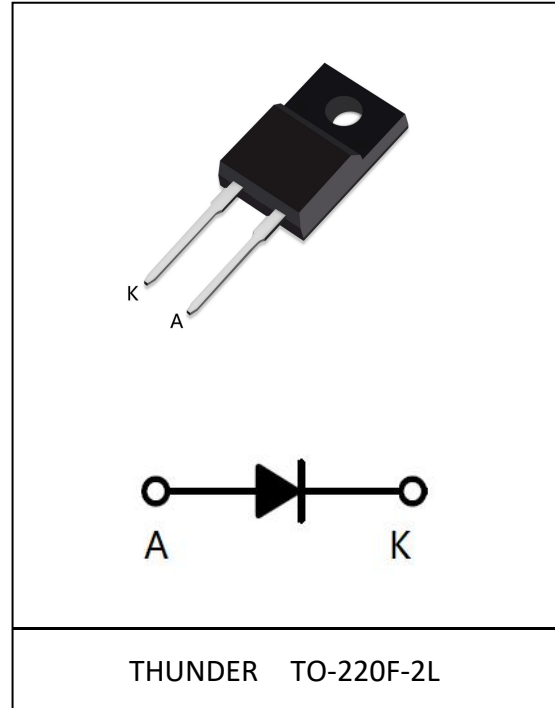
FRED

Ultrafast Soft Recovery Diode, 30A

Features:

- Ultrafast Recovery
- 175°C operating junction temperature
- High frequency operation
- Low power loss, less RFI and EMI
- Low I_R value
- High surge capacity
- Epitaxial chip construction

Product Summary	
V_R	600V
$I_{F(AV)}$	30A
t_{rr}	24ns



Description/Applications

These diodes are optimized to less losses and EMI/RFI in high frequency power conditioning system. The soft recovery behavior of the diodes offers the need as snubber in most applications. These devices are ideally suited for applications where the switching losses are not significant portion of the total losses.

Absolute Maximum Ratings

Parameter	Symbol	Test Conditions	Values	Units
Repetitive peak reverse voltage	V_{RRM}		600	V
Continuous forward current	$I_{F(AV)}$	$T_c = 110^\circ\text{C}$	30	A
Single pulse forward current	I_{FSM}	$T_c = 25^\circ\text{C}$	300	
Maximum repetitive forward current	I_{FRM}	Square wave, 20kHz	55	
Operating junction	T_j		175	$^\circ\text{C}$
Storage temperatures	T_{stg}		-55 to +175	$^\circ\text{C}$

Electrical characteristics (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ.	Max.	Units
Breakdown voltage Blocking voltage	V_{BR} , V_R	$I_R=100\mu A$	600			V
Forward voltage	V_F	$I_F=30A$		1.70	2.10	
		$I_F=30A, T_J=125^\circ C$		1.45	1.90	
Reverse leakage current	I_R	$V_R=V_{RRM}$			20	μA
		$T_J=150^\circ C, V_R=600V$			200	
Reverse recovery time	t_{rr}	$I_F=1A, V_R=30V, di/dt=200A/\mu s$		24	35	ns
Reverse recovery time	t_{rr}	$I_F=30A, V_R=300V,$ $dI_F/dt=-200A/\mu s, T_J=25^\circ C$		30		ns
Maximum Reverse Recovery Current	I_{RM}			4.1		A
Reverse Recovery Charge	Q_{rr}			156		nC
Reverse recovery time	t_{rr}	$I_F=30A, V_R=300V,$ $dI_F/dt=-200A/\mu s, T_J=125^\circ C$		95		ns
Maximum Reverse Recovery Current	I_{RM}			8		A
Reverse Recovery Charge	Q_{rr}			950		nC

Thermal characteristics

Paramter	Symbol	Typ	Units
Junction-to-Case	$R_{\theta JC}$	2.0	$^\circ C/W$

Electrical performance (typical)

FIG.1 Forward Characteristic (typical)

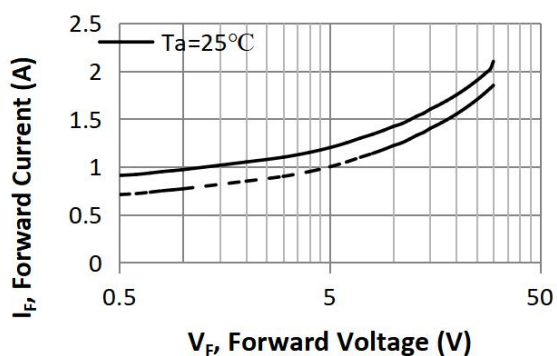


FIG.2 Reverse Characteristic (typ.)

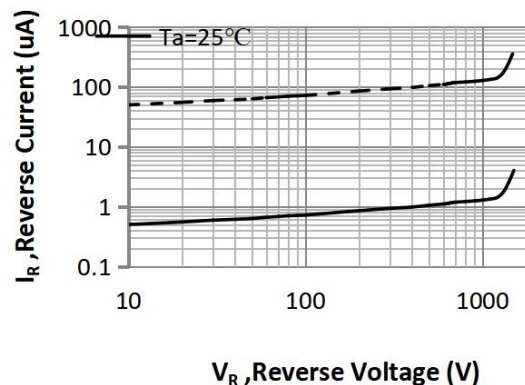


FIG.3 Reverse Recover Time vs. Current Rate of Change

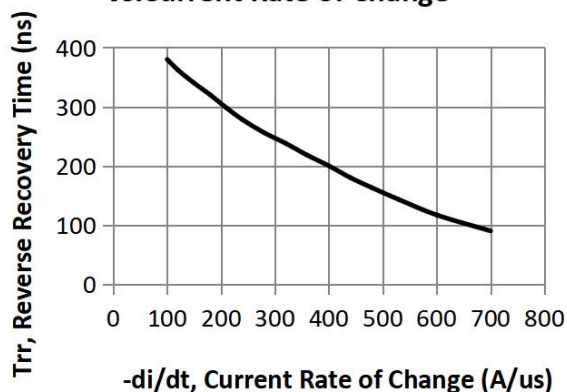


FIG.4 Reverse Recover Charge vs. Current Rate of Change

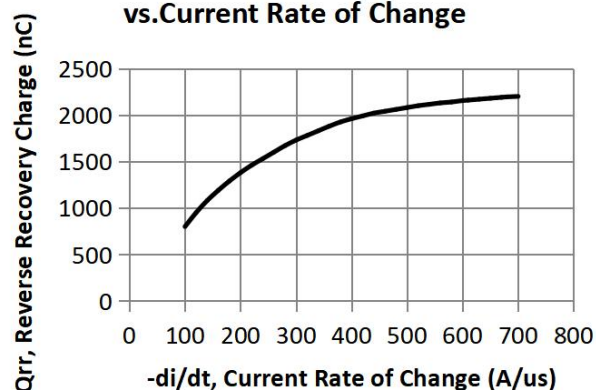


FIG.5 Reverse Recover Current vs. Current Rate of Change

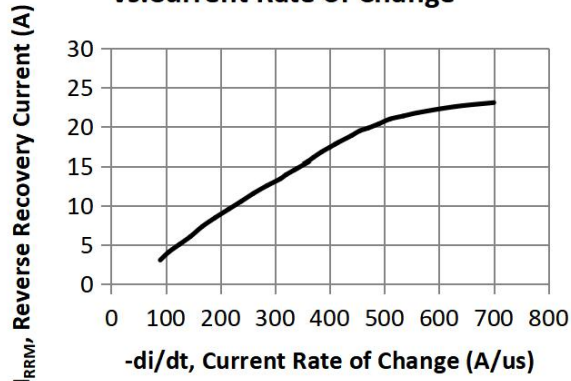
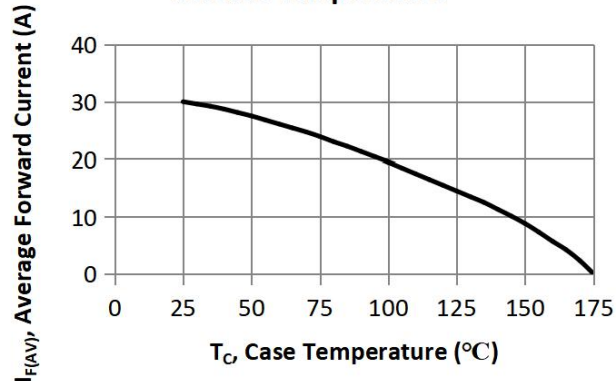


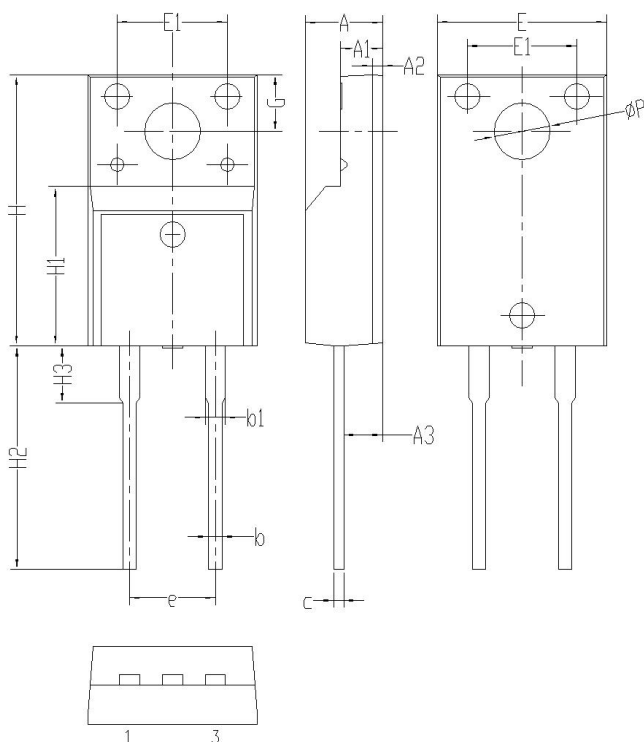
FIG.6 Average Forward Current vs. Case Temperature



Package Information

TO-220F-2L PACKAGE

基本尺寸



Symbol	单位 mm		
	Min	Nom	Max
A	4.55	4.75	4.95
A1	2.40	2.60	2.80
A2	0.40	0.60	0.80
A3	2.10	2.30	2.50
b1	1.10	1.30	1.50
b	0.60	0.80	1.00
c	0.42	0.50	0.58
e	4.88	5.08	5.28
E	9.9	10.1	10.3
E1	6.8	7	7.2
H	15.8	16.0	16.2
H1	9.10	9.30	9.50
H2	12.5	13.0	13.5
H3	3.10	3.30	3.50
G	3.00	3.20	3.40
ΦP	3.00	3.20	3.40

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